

# Electronic Filing System (EFS) Data Electronic Patent Application Submission USPTO Use Only

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Application ID:

10763859

Title of Invention:

SEMICONDUCTOR PACKAGE

HAVING REDUCED THICKNESS

First Named Inventor:

TAE LEE

Domestic/Foreign Application:

**Domestic Application** 

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8528

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### TRANSMITTAL

Electronic Version v1.1 Stylesheet Version v1.1.0

> Title of Invention

SEMICONDUCTOR PACKAGE HAVING REDUCED THICKNESS

Application Number:

10/763859

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2004-01-23

First Named Applicant: TAE HEON LEE

Confirmation Number:

8528

Attorney Docket Number: AMKOR053G

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Submitted by:	Elec. Sign.	Sign. Capacity	
MARK B. GARRED Registered Number: 34,823	/mbg/	Attorney	

Documents being submitted

**Files** 

us-ids

ids4-usidst.xml

us-ids.dtd

us-ids.xsl

Comments



## ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18 Stylesheet Version v18.0

> Title of Invention

SEMICONDUCTOR PACKAGE HAVING REDUCED **THICKNESS** 

Application Number:

10/763859

Confirmation Number:

8528

First Named Applicant:

TAE LEE

Attorney Docket Number: AMKOR053G

Art Unit:

2811

Search string:

(5886398 or 5894108 or 5897339 or 5900676 or 5903049 or 5903050 or 5909053 or 5915998 or 5917242 or 5939779 or 5942794 or 5951305 or 5959356 or 5969426 or 5973388 or 5976912 or 5977613 or 5977615 or 5977630 or 5981314 or 5986333 or 5986885 or 6001671 or 6013947 or 6018189 or 6020625 or 6025640 or 6031279 or 6034423 or RE36613 or 6040626 or 6043430 or 6060768 or 6060769 or 6072228 or 6075284 or 6081029 or 6084310 or 6087715 or 6087722 or 6100594 or 6114752 or 6113474 or 6118174 or 6118184 or 6130115 or 6130473 or RE36907

or 6133623 or 6140154 ).pn.

#### **US Patent Documents**

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

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## Signature

Examiner Name	Date